

MultiTech xDot* is a secure, end-certified, Arm* Mbed™ programmable, low-power RF module, that provides long-range, low bit rate M2M data connectivity to sensors, industrial equipment and remote appliances.

The xDot is LoRaWAN* 1.0.2 compliant, providing bi-directional data communication up to 10 miles / 15 km line-of-sight and 1-3 miles / 2 km into buildings**, using sub-GHz ISM bands in North America, Europe, Australia (AU915), Asia Pacific (AS923), India (IN865) and Korea (KR920).

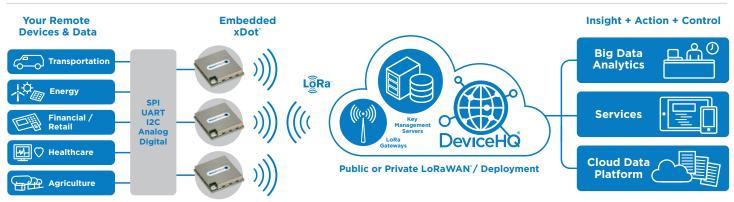
xDots bring intelligence, reduced complexity and a lower overall bill of material cost to the very edge of the network while supporting a variety of electronic interfaces to connect just about any "Thing" for years on battery power.

BENEFITS

- Range of miles
- Deep in-building penetration
- Developer friendly
- Runs for years on batteries

FEATURES

- End-certified for use in North America, Europe, Australia, Japan, Korea & India
- LoRaWAN Certified[™]
- Unicast & Multicast message support
- Multiple I/O interfaces for most any "Thing"
- Data rates
 293bps-20Kbps+ LoRa*
- Listen-Before-Talk (LBT) enabled in Japan & Korea models



SPECIFICATIONS

Models	MTXDOT-AS1	MTXDOT-AU1	MTXDOT-EU1		
Region/Country	Asia Pacific (**)	Australia	Europe		
LoRa Radio Frequency Plan	AS920-923 ("AS1")	AU915-928	EU863-870		
Listen-Before-Talk (LBT) Enabled	No				
Channel Capacity	8-channels				
Range	Up to 10 miles (15 km) line of sight 1 - 3 miles (2km) into buildings				
Communication	LoRaWAN 1.0.2 compliant, Class A and Class C Arm Mbed libraries or AT commands for radio control				
Interfaces	Up to 19 Digital I/O, 10 Analog Inputs, 2 DAC Outputs, 12C, SPI, Wake Pin, Reset Pin, Full UART, MBED / simple UART (RX & TX only), MBED Programming Interface				
Physical Dimensions	23.6 mm X 23.6 mm x 3.51 (.93" x .93" x 0.14")				
Performance					
CPU	ST Micro ST32L151CCU6 (ARM® Cortex®-M3) 32 MHz				
Max Clock	32 MHz				
Flash Memory	256 KB, with xDot library 136 KB available; with AT firmware, 56 KB available				
EEPROM	8 KB, available 6 KB				
SRAM	32 KB				
Backup Register	128 byte, available 88 bytes				
Power					
Max Transmitter Power Output (TPO)	19 dBm	19 dBm	14 dBm		
Max Receive Sensitivity	-130 dBm	-130 dBm	-137 dBm		
Link Budget (*)	145 dB Point-to-Multipoint 147 dB Point-to-Point	145 dB Point-to-Multipoint 147 dB Point-to-Point	151 dB Point-to-Multipoin 147 dB Point-to-Point		
Deep Sleep Current	< 2uA				
Max Effective Isotropic Radiated Power (EiRP)	36 dBm	36 dBm	10 dBm		

(*) Calculation assumes two 0 dBi antennas. North America: Greater link budget possible with higher gain antennas. Europe: This is the maximum link budget. Note: Point-to-Multipoint utilizing MultiTech Conduit Gateway with MTAC-LORA accessory card.

Antenna Connector Options					
-A00 Models	U.FL and Trace (ULF/TRC)				
-A01 Models	Trace only (TRC)				
Environmental					
Operating Temperature	-40° C to +85° C (-40° F to +185° F)				
Storage Temperature	-40° C to +85° C (-40° F to +185° F)				
Relative Humidity	20% to 90% RH noncondensing				
Certifications					
EMC Compliance	Contact MultiTech	AS/NZS CISPR 22	EN 55022 Class B, EN 55024 CISPR 22:2008		
Radio Compliance	Contact MultiTech	AS/NZS 4268:2012 + a1:2013 MPE Standard 2014	EN 300 220-2 V2.4.1:2012 EN 301 489-03 V1.6.1:2013		
Safety	Contact MultiTech	AS/NZS 60950.1:2015	IEC 60950-1 2nd ED AM1 + AM2		
Quality	MIL-STD-810G: High Temp, Low Temp, Random Vibration. SAE J1455: Transit Drop & Handling Drop, Random Vibration, Swept-Sine Vibration. IEC68-2-1: Cold Temp. IEC68-2-2: Dry Heat				

^(**) Actual performance speeds may be affected by a variety of attributes such as distance from gateway, data loads, packet sizes, etc. Note: AS923 models are for use in many Asia Pacific countries. Contact your MultiTech sales representative for more information.

SPECIFICATIONS

Models	MTXDOT-EU1-IN1	MTXDOT-JP1	MTXDOT-KR1	MTXDOT-NA1	
Region/Country	India	Japan	Korea	North America	
LoRa Radio Frequency Plan	IN865-867	AS920-923 ("AS1")	KR920-923	US902-928	
Listen-Before-Talk (LBT) Enabled	No	Yes		No	
Channel Capacity	8-channels				
Range	Up to 10 miles (15 km) line of sight 1 - 3 miles (2km) into buildings				
Communication	LoRaWAN 1.0.2 compliant, Class A and Class C Arm Mbed libraries or AT commands for radio control				
Interfaces	Up to 19 Digital I/O, 10 Analog Inputs, 2 DAC Outputs, I2C, SPI, Wake Pin, Reset Pin, Full UART, MBED / simple UART (RX & TX only), MBED Programming Interface				
Physical Dimensions		23.6 mm X 23.6 mm x	3.51 (.93" x .93" x 0.14")		
Performance					
CPU	ST Micro ST32L151CCU6 (ARM® Cortex®-M3) 32 MHz				
Max Clock	32 MHz				
Flash Memory	256 KB, with >	256 KB, with xDot library 136 KB available; with AT firmware, 56 KB available			
EEPROM	8 KB, available 6 KB				
SRAM	32 KB				
Backup Register	128 byte, available 88 bytes				
Power					
Max Transmitter Power Output (TPO)	14 dBm	19 dBm	19 dBm	19 dBm	
Max Receive Sensitivity	-137 dBm	-130 dBm	-130 dBm	-130 dBm	
Link Budget (*)	151 dB Point-to- Multipoint 147 dB Point-to-Point	145 dB Point-to- Multipoint 147 dB Point-to-Point	145 dB Point-to- Multipoint 147 dB Point-to-Point	145 dB Point-to- Multipoint 147 dB Point-to-Point	
Deep Sleep Current	< 2uA				
Max Effective Isotropic Radiated Power (EiRP)	10 dBm	36 dBm	36 dBm	36 dBm	

(*) Calculation assumes two 0 dBi antennas. North America: Greater link budget possible with higher gain antennas. Europe: This is the maximum link budget. Note: Point-to-Multipoint utilizing MultiTech Conduit Gateway with MTAC-LORA accessory card.

Antenna Connector Options					
-A00 Models	U.FL and Trace (ULF/TRC)				
-A01 Models	Trace only (TRC)				
Environmental					
Operating Temperature	-40° C to +85° C (-40° F to +185° F)				
Storage Temperature	-40° C to +85° C (-40° F to +185° F)				
Relative Humidity	20% to 90% RH noncondensing				
Certifications					
EMC Compliance	EN 55022 Class B, EN 55024 CISPR 22:2008	TELEC, Radio/ Telecom Biz Act, GITEKI	National Radio Research Agency Notice 2018-29	US: FCC Part 15 Class B Canada: ICES-003 Mexico: TBD	
Radio Compliance	EN 300 200	Japan Giteki, Radio/ Telecom Biz Act	Ministry of Science and ICT Notice 2018-90	FCC 15.247:2015 FCC 15.109:2015 FCC 15.107:2015	
Safety	IEC 60950-1 2nd Ed AM1 & AM2	IEC 60950-1 2nd Ed AM1 & AM2	62368-1	US: UL 60950-1 2nd ED Canada: cUL 60950-1 2nd ED Mexico: TBD	
Quality	MIL-STD-810G: High Temp, Low Temp, Random Vibration. SAE J1455: Transit Drop & Handling Drop, Random Vibration, Swept-Sine Vibration. IEC68-2-1: Cold Temp. IEC68-2-2: Dry Heat				

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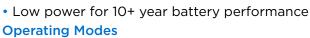
EDGE INTELLIGENCE

The MultiTech xDot* is Arm* Mbed™ compatible meaning applications can be written and compiled quickly online using developer friendly libraries, downloaded and hosted within the xDot. Decision making and control is distributed to the edge, enabling data to be more actionable without the heavy lift required to optimize RF performance, implement complex IoT middleware and security protocols needed to deploy a low touch install. In addition, xDots come from the factory with AT command firmware preloaded. This means you can use the xDot as an AT command driven LoRa modem. No custom software development for the xDot is needed when operating in this mode.

HIGHLIGHTS

Applications

- Securely manage and harvest sensor data
- Control and monitor remote assets and devices



- Developer friendly Arm Mbed libraries provides customization capability for specific applications
- Comprehensive AT command instruction set

DEVELOPER KIT

The MultiTech xDot (MTMDK-XDOT)
Micro Developer Kit is a USB dongle
that allows a developer to plug in a
MultiTech xDot (MTXDOT-XXX)
and start developing their application.
Its portable design makes it ideal for
connecting to a laptop and doing
range testing of the LoRa network.
This kit includes a development board,
xDot, integrated LoRa antenna and
Quick Start Guide.



YOU MAY ALSO BE INTERESTED IN: MULTITECH CONDUIT® FAMILY

xDot LGA

Family Footprint

MultiTech Conduit® family of products is the industry's most configurable, manageable, and scalable cellular communications gateways for industrial IoT applications. Network engineers can remotely configure and optimize their Conduit performance through DeviceHQ®, the world's first IoT Application Store and Device Management platform.

MultiTech Conduit

The award-winning Conduit series comes in three variants designed to address specific IoT gateway use cases:

- MultiTech Conduit: Indoor industrial gateway, ideal for environments that require metal casing for protection against particles and debris and require an industrial temperature range.
- MultiTech Conduit IP67 Base Station: Outdoor
 IP67-rated gateway ideal suited for performing in harsh environments such as rain, snow, extreme heat, and high winds.
- MultiTech Conduit AP: Indoor access point ideal for commercial environments (e.g., hotels, offices, retail facilities) to deepen LoRa coverage in difficult to reach places where cell tower or rooftop deployments may not perform as well.



MultiTech Conduit® AP Access Point